



Liu et al.  
Serial No. 09/208,963  
Filed December 10, 1998

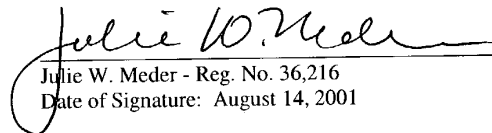
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of )  
John Liu et al. ) Examiner Harry D. Wilkins III  
Serial No. 09/208,963 ) Group Art Unit 1742  
Confirmation No. 8859 ) Attorney Docket 97-2739  
Filed December 10, 1998 )  
For High Toughness Plate Alloy For )  
Aerospace Applications )

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AMENDMENT

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on August 14, 2001.

  
Julie W. Meder - Reg. No. 36,216  
Date of Signature: August 14, 2001

Assistant Commissioner for Patents

Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Office Action dated May 10, 2001, Applicants submit the following amendments and remarks.

IN THE SPECIFICATION:

Please delete the paragraph bridging pages 3 and 4 and the first full paragraph on page 4, and replace them with the following replacement paragraphs. Pursuant to 37 CFR § 1.121 the following are clean copies of the replacement paragraphs. Marked-up versions are attached on separate sheets.